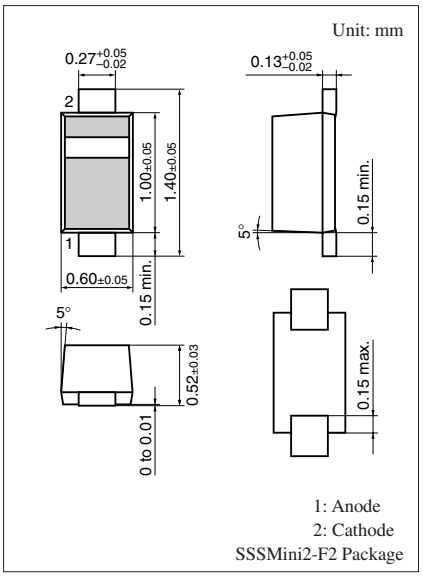
MA27784

Silicon epitaxial planar type

For high-speed switching circuits



Marking Symbol: P

■ Features

- High-density mounting is possible
- Low forward voltage V_F and good rectification efficiency
- Optimum for high frequency rectification because of its short reverse recovery time t_{rr}

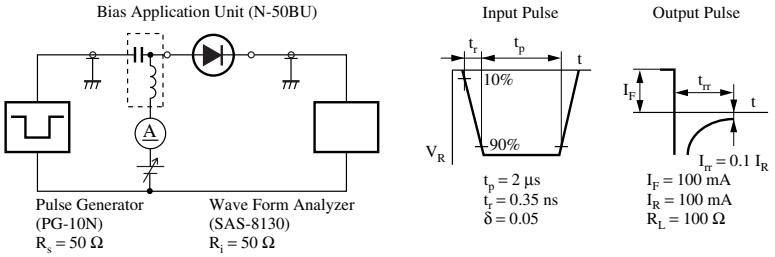
■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Repectitive peak reverse voltage	V_{RRM}	30	V
Forward current (Average)	$I_{F(AV)}$	100	mA
Peak forward current	I_{FM}	300	mA
Non-repetitive peak forward surge current	I_{FSM}	1	A
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	−55 to +125	°C

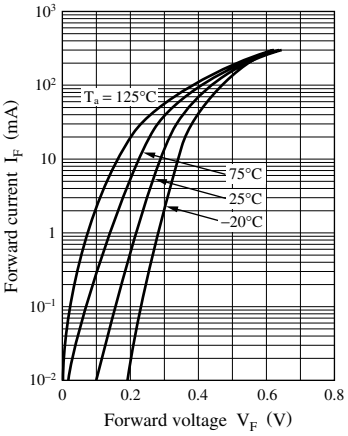
■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	I_F = 100 mA			0.55	V
Reverse current	I_R	V_R = 30 V			15	µA
Terminal capacitance	C_t	V_R = 0 V, f = 1 MHz		20		pF
Reverse recovery time *	t_{rr}	$I_F = I_R$ = 10 mA I_{rr} = 0.1 I_R , R_L = 100 Ω		2.0		ns

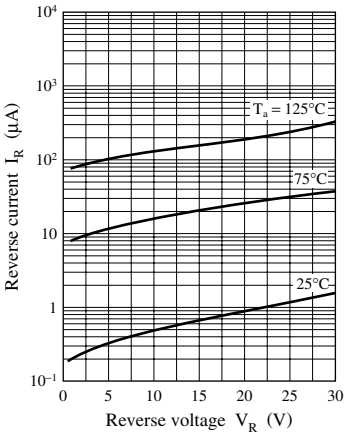
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Absolute frequency of input and output is 250 MHz
4. *: t_{rr} measurement circuit



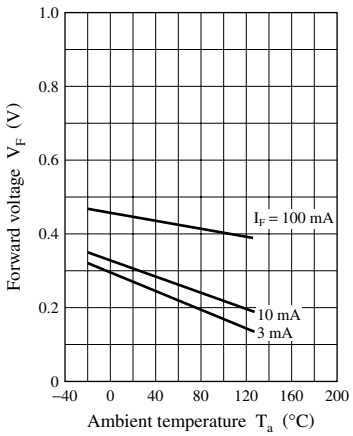
I_F — V_F



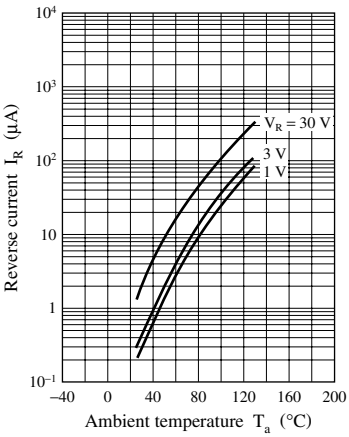
I_R — V_R



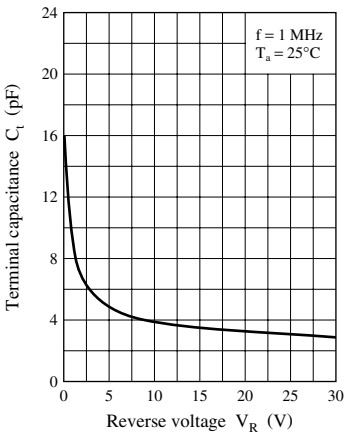
V_F — T_a



I_R — T_a



C_t — V_R



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